

"Chip Testing Within a Multi-Chip Semiconductor Package" . Inventor: Adrian E. Ong Appln. Serial No.: 10/824,734 Atty. Docket No.: 24295/81003

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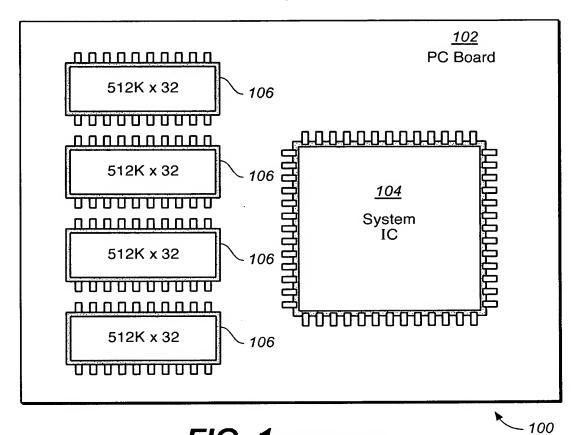


FIG. 1 (PRIOR ART)

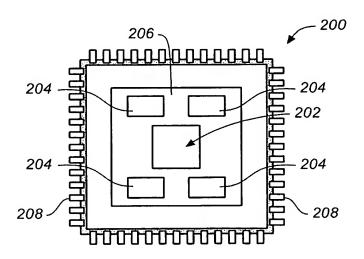
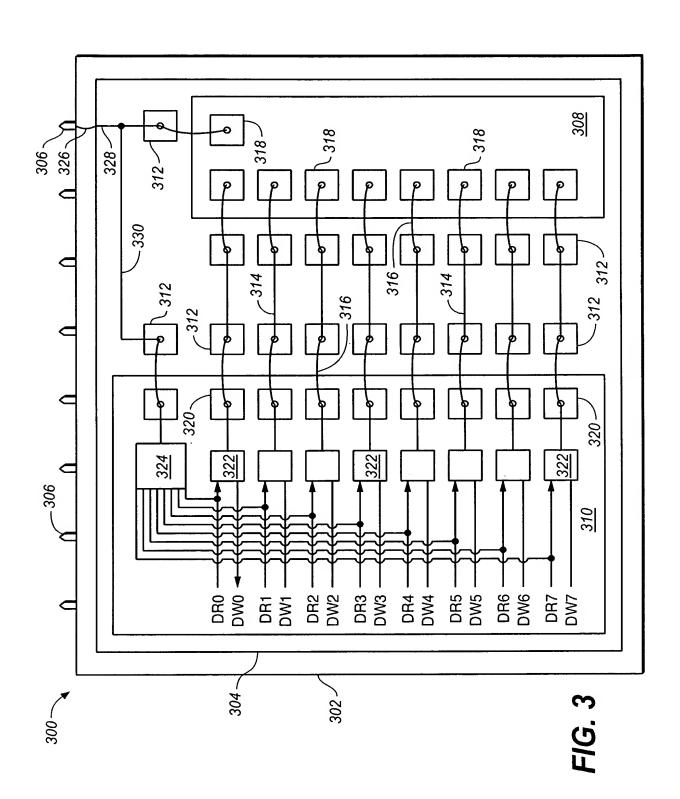


FIG. 2 (PRIOR ART)

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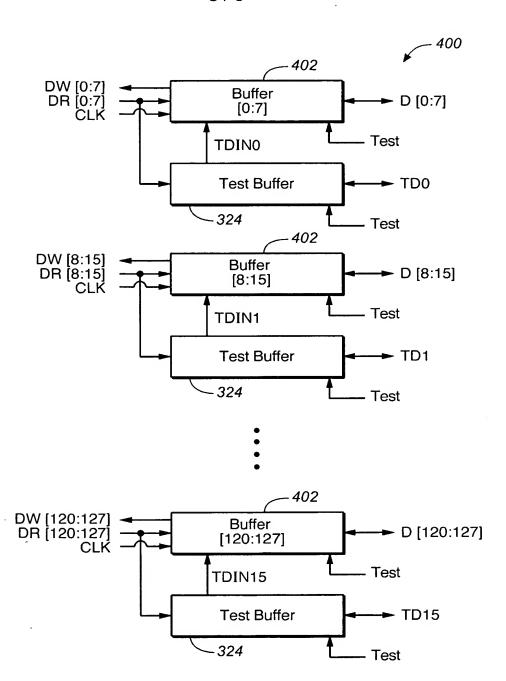


FIG. 4

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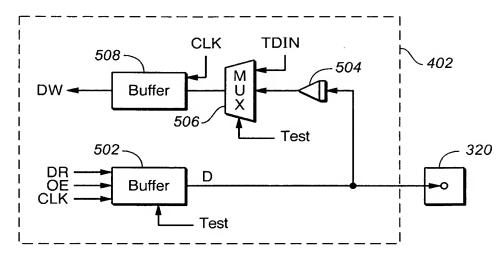
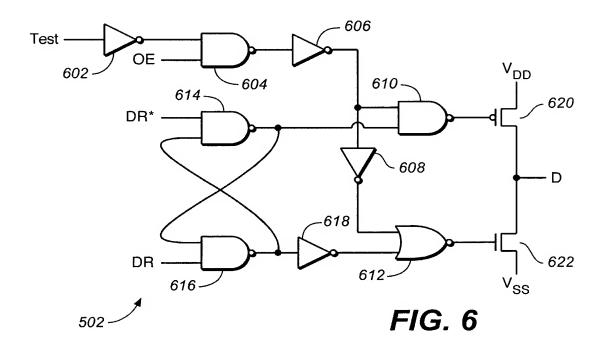
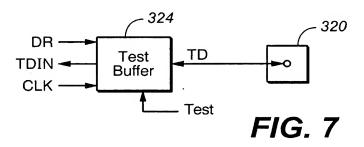


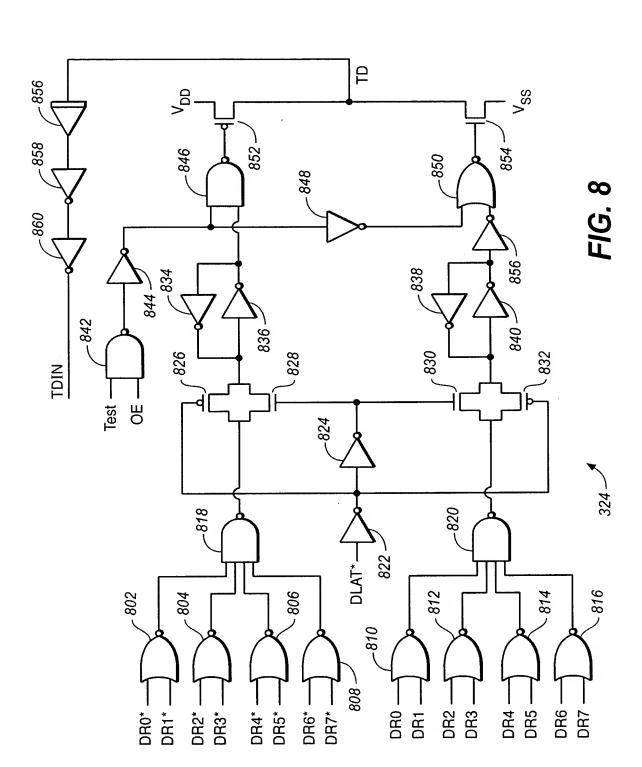
FIG. 5





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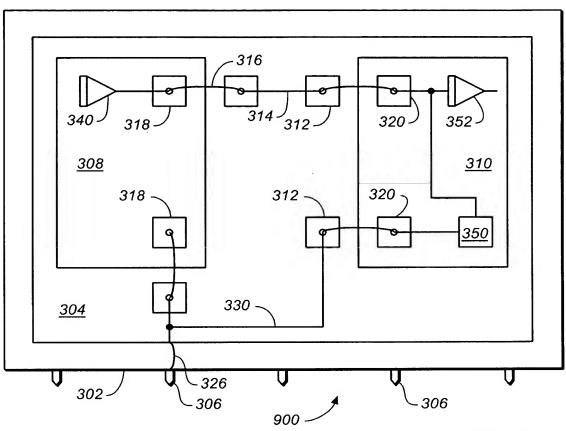


FIG. 9

